



3D Packaging & Integration North America TC Chapter

NA Standards Spring Meeting 2023

Thursday, April 6

SEMI Headquarters, Milpitas, California/USA

13:00–14:30 Noon (Pacific) Hybrid

AGENDA

	Time
1 Welcome/Call to Order	13:00
1.1 Please log into www.svm.semi.org for voting	
1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)	
1.3 Agenda Review	
1.4 Introductions	
2 Liaison Reports	13:15
2.1 Japan TC Chapter	
2.2 Taiwan TC Chapter	
3 Staff Report	13:20
4 Review of Previous Meeting Minutes	13:30
5 Ballot Review (None)	
6 Task Force Updates	13:40
6.1 3DP&I Bonded Wafer Stacks Task Force	
6.2 3DP&I Inspection & Metrology Task Force	
6.3 Panel Level Packaging (PLP) Panel Task Force	
7 Old Business	14:10
7.1 Five-Year Review	



	Time
8 New Business	14:20
9 Action Item Review	14:25
10 Next Meeting and Adjournment	14:30
10.1 The next meeting is tentatively scheduled for the week of July 10-13, in conjunction with SEMICON West 2023. Schedule details TBD. Please check www.semi.org/standards for updates.	

Tentative Schedule:

- Thursday, July 13 ?
 - 11:00-12:00, Joint 3DP&I Bonded Wafer Stacks Task Force, and 3DP&I Inspection & Metrology Task Force
 - TBD, PLP Panel TF
 - 13:00-14:30, 3DP&I NA TC Chapter

20230330
LNN
v1

STANDARDS VIRTUAL MEETING INFORMATION LINK

<https://www.semi.org/en/semi-standards-spring-meetings-2023-virtual-information>

Password was sent to TC Membership and those registered for the meetings.

NOTE:

Standards meetings are open to all, but you must be a SEMI Standards Program Member to attend.

If you are not a member, please register for the International SEMI Standards Program here:

<https://www.semi.org/standardsmembership>